MET5 MATERIAL PROCESSING
SCREEN SK80EX

- 200 mm wafers
- $\text{H}_2\text{O}$-based processing
- Non-$\text{H}_2\text{O}$-based processing
- 4 hot plates (250C)
- 2 chill plates
- 1 HMDS (vapor)
- Ellipsometry / Thickness
H₂O-BASED PROCESSING

• Plumbed TMAH (2.3 wt. % in H₂O)
• Plumbed DI H₂O
• Plumbed Surfactant Rinse (TBD)
• Spare Plumbed Aqueous Developer (TBD)
• Manual Syringe Dispense for everything else
NON-H₂O-BASED PROCESSING

- Plumbed 2-Heptanone (Develop or Pre-Wet)
- Plumbed 70/30 PGME/PGMEA (Bowl Rinse, Edge Bead Removal, Back Side Rinse, Pot Rinse)
- Automated syringe dispense for everything else (resists, ULs)
- Split drain for material compatibility